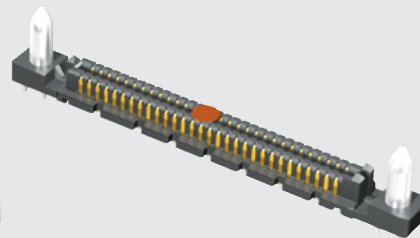


SEAM-20-01-L-06-2-RA-GP-TR



SEAM-30-02.0-L-04-2-A-GP-K-TR

(1,27 mm) .050"

SEAM-RA, SEAM-GP SERIES

# HI-DENSITY RIGHT ANGLE OPEN PIN FIELD

**SEAM-RA Mates with:**  
SEAF, SEAF-RA, SEAFP

**SEAM-GP Mates with:**  
SEAF-RA-GP

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM-RA](http://www.samtec.com?SEAM-RA) or [www.samtec.com?SEAM](http://www.samtec.com?SEAM)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Current Rating:**

SEAM-RA = 2.0 A per pin  
(6 adjacent pins powered)

**Operating Temp Range:**

-55°C to +125°C

**Plating:**

Au or Sn over  
50 μm (1,27 μm) Ni

**Contact Resistance:**

SEAM-RA = 19 mΩ

SEAM-GP = 5.5 mΩ

**Working Voltage:**

SEAM-RA = 260 VAC

SEAM-GP = 240 VAC

**Mated Cycles:**

SEAM-GP = 100

**RoHS Compliant:**

Yes

**Lead-Free Solderable:**

Yes

SEAM	NO. PINS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	TR
	-20, -30, -40, -50		-L = 10 μm (0,25 μm) Gold on contact area, Matte Tin on solder tail  -S = 30 μm (0,76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows  -06 = Six Rows  -08* = Eight Rows  -10* = Ten Rows	-1 = Tin/Lead Alloy Solder Charge  -2 = Lead-Free Solder Charge		-GP = Guide Post  -K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

NO. PINS PER ROW	A
-20	(38,94) 1.533
-30	(51,64) 2.033
-40	(64,34) 2.533
-50	(77,04) 3.03

TEST DATA*	SEAM-RA/SEAF-05	SEAM-RA/SEAF-RA
Single-Ended	23 Gbps	24 Gbps
Differential Pair	23 Gbps	22 Gbps

\* @ 3dB insertion loss. Test board losses de-embedded from performance data.  
Complete test data available at [www.samtec.com?SEAM-RA](http://www.samtec.com?SEAM-RA) or contact [sig@samtec.com](mailto:sig@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

SEAM	NO. PINS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	TR
	-20, -30, -40, -50		-L = 10 μm (0,25 μm) Gold on contact area, Matte Tin on solder tail  -S = 30 μm (0,76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows  -06 = Six Rows  -08 = Eight Rows  -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge  -2 = Lead-Free Solder Charge			-K = Polyimide film Pick & Place Pad  -TR = Tape & Reel (Not available with 50 positions)	

### ALSO AVAILABLE (MOQ Required)

- Extended Guide Post
  - Guide post Field termination kits
  - Other platings
- Contact Samtec.

Note: SEAM-GP Patented

Note: Some sizes, styles and options are non-standard, non-returnable.